

IMPROVED LEADFRAME-BASED CHIP SCALE PACKAGE

ABSTRACT OF THE DISCLOSURE

An improved leadframe-based CSP and a method of forming the leadframe-based CSP are provided. The leadframe-based CSP includes a leadframe including a die attach pad and a plurality of wire bonding pads, at least one aperture disposed in the die attach pad, at least one die on the die attach pad, at least one bonding wire for electrically connecting the die and the wire bonding pads, and a mold compound for encapsulating the die and the bonding wire to form a chip package, wherein the mold compound is formed in the aperture.

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